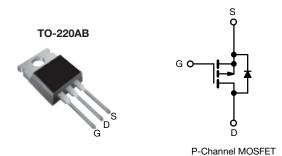


# **Power MOSFET**



PRODUCT SUMMAI	RY	
V <sub>DS</sub> (V)	-10	00
$R_{DS(on)}(\Omega)$	$V_{GS} = -10 \text{ V}$	0.20
Q <sub>g</sub> max. (nC)	6	1
Q <sub>gs</sub> (nC)	1-	4
Q <sub>gd</sub> (nC)	2	9
Configuration	Sin	gle

#### **FEATURES**

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

## **DESCRIPTION**

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF9540PbF
Lead (Pb)-free and halogen-free	IRF9540PbF-BE3

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	-100	V	
Gate-source voltage		$V_{GS}$	± 20	V	
Continuous drain current	V at 10 V	T <sub>C</sub> = 25 °C		-19	
Continuous drain current	V <sub>GS</sub> at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I <sub>D</sub>	-13	Α
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	-72	
Linear derating factor				1.0	W/°C
Single pulse avalanche energy b			E <sub>AS</sub>	640	mJ
Repetitive avalanche current a			I <sub>AR</sub>	-19	А
Repetitive avalanche energy <sup>a</sup>			E <sub>AR</sub>	15	mJ
Maximum power dissipation T <sub>C</sub> = 25 °C		25 °C	$P_{D}$	150	W
ak diode recovery dV/dt c dV/dt -5.5		V/ns			
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Soldering recommendations (peak temperature) <sup>d</sup>	For	10 s	-	300	
Manuating tagging	6.00.0*1	6-32 or M3 screw		10	lbf ⋅ in
Mounting torque	1.1	1.1	N⋅m		

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b.  $V_{DD} = -25$  V, starting  $T_J = 25$  °C, L = 2.7 mH,  $R_q = 25$   $\Omega$ ,  $I_{AS} = -19$  A (see fig. 12)
- c.  $I_{SD} \le -19$  A,  $dI/dt \le 200$  A/ $\mu$ s,  $V_{DD} \le V_{DS}$ ,  $T_{J} \le 175$  °C
- d. 1.6 mm from case



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# Vishay Siliconix

THERMAL RESISTANCE RAT	INGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62	
Case-to-sink, flat, greased surface	R <sub>thCS</sub>	0.50	-	°C/W
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	1.0	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•		·
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-100	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I <sub>D</sub> = -1 mA	-	-0.087	-	V/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V$	/ <sub>GS</sub> , I <sub>D</sub> = -250 μA	-2.0	-	-4.0	V
Gate-source leakage	I <sub>GSS</sub>	Vo	<sub>GS</sub> = ± 20 V	-	-	± 100	nA
<b>7</b>		V <sub>DS</sub> = -	100 V, V <sub>GS</sub> = 0 V	-	-	-100	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = -80 \text{ V},$	V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C	-	-	-500	μΑ
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -11 A <sup>b</sup>	-	-	0.20	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = -	50 V, I <sub>D</sub> = -11 A <sup>b</sup>	6.2	-	1	S
Dynamic							•
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 V$ ,		-	1400	-	pF
Output capacitance	C <sub>oss</sub>	V	$V_{GS} = 0 \text{ V},$ $V_{DS} = -25 \text{ V},$		590	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1.0	MHz, see fig. 5	-	140	-	1
Total gate charge	Qg			-	-	61	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = -10 V	$I_D = -19 \text{ A}, V_{DS} = -80 \text{ V},$ see fig. 6 and 13 b	-	-	14	nC
Gate-drain charge	Q <sub>gd</sub>		See lig. 0 and 15	-	-	29	
Turn-on delay time	t <sub>d(on)</sub>			-	16	-	
Rise time	t <sub>r</sub>	$V_{DD}$ = -50 V, $I_D$ = -19 A, $R_g$ = 9.1 $\Omega$ , $R_D$ = 2.4 $\Omega$ , see fig. 10 <sup>b</sup>		-	73	-	ns
Turn-off delay time	t <sub>d(off)</sub>			-	34	-	
Fall time	t <sub>f</sub>			-	57	-	
Gate input resistance	$R_g$	f = 1 MHz, open drain		0.3	-	1.6	Ω
Internal drain inductance	L <sub>D</sub>	6 mm (0.25")	Between lead, 6 mm (0.25") from		4.5	ı	nH
Internal source inductance	L <sub>S</sub>	package and center of die contact		-	7.5	-	
<b>Drain-Source Body Diode Characteristic</b>	cs						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	-19	А
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>			-	-	-72	
Body diode voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I	<sub>S</sub> = -19 A, V <sub>GS</sub> = 0 V <sup>b</sup>	-	-	-5.0	V
Body diode reverse recovery time	t <sub>rr</sub>	T 05 00 1	40 A -11/-14 - 400 A / - b	-	130	260	ns
Body diode reverse recovery charge	Q <sub>rr</sub>	$T_J = 25 ^{\circ}\text{C}, I_F = -19 \text{A}, dI/dt = 100 \text{A/}\mu\text{s}^{\text{b}}$		-	0.35	0.70	μC
Forward turn-on time	t <sub>on</sub>	Intrinsic turr	n-on time is negligible (turn	on is do	minated b	v L <sub>S</sub> and	L <sub>D</sub> )

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width  $\leq$  300  $\mu$ s; duty cycle  $\leq$  2 %



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

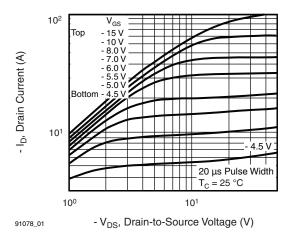


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

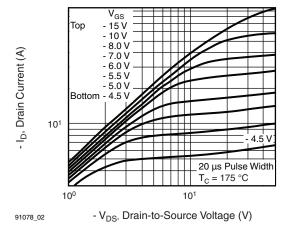


Fig. 2 - Typical Output Characteristics,  $T_C$  = 175  $^{\circ}$  C

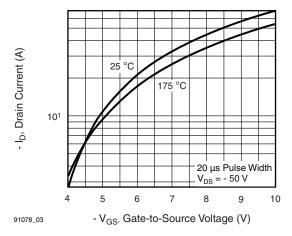


Fig. 3 - Typical Transfer Characteristics

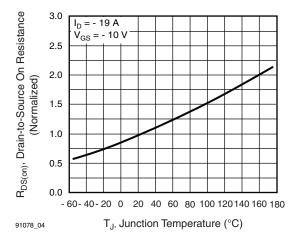


Fig. 4 - Normalized On-Resistance vs. Temperature

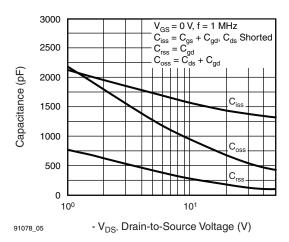


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

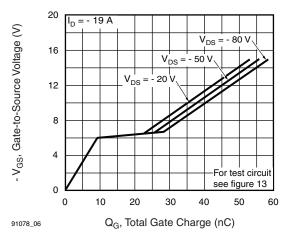


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



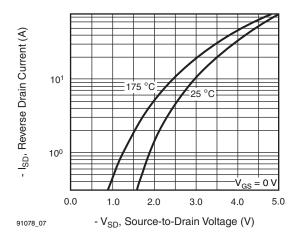


Fig. 4 - Typical Source-Drain Diode Forward Voltage

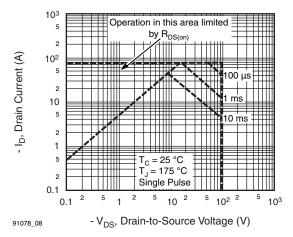


Fig. 5 - Maximum Safe Operating Area

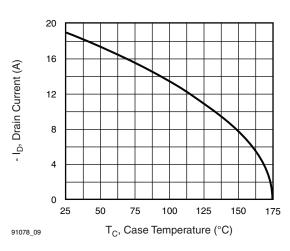


Fig. 6 - Maximum Drain Current vs. Case Temperature

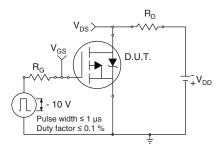


Fig. 10a - Switching Time Test Circuit

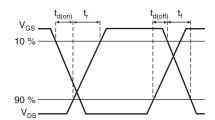


Fig. 10b - Switching Time Waveforms

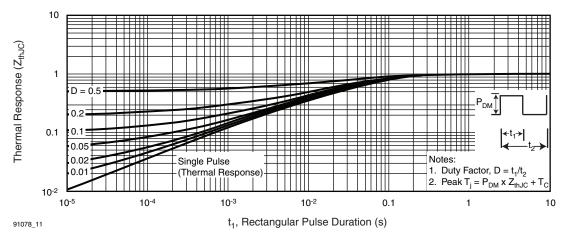


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



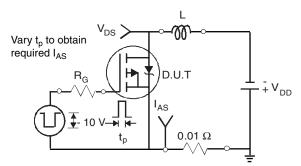


Fig. 12a - Unclamped Inductive Test Circuit

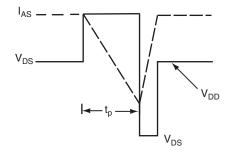


Fig. 12b - Unclamped Inductive Waveforms

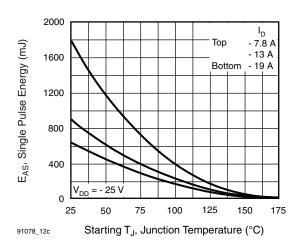


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

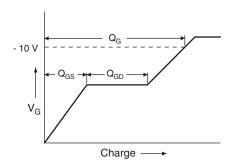


Fig. 13a - Basic Gate Charge Waveform

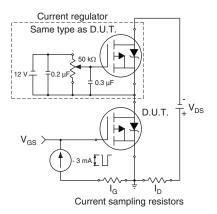
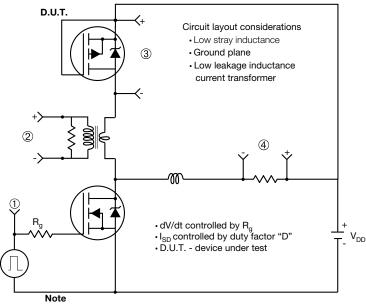


Fig. 13b - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



• Compliment N-Channel of D.U.T. for driver

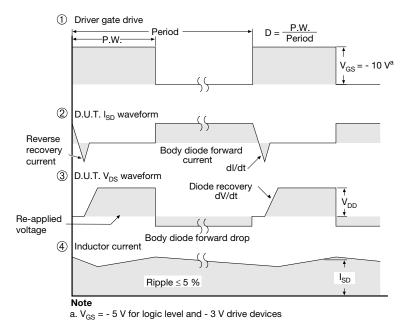


Fig. 14 - For P-Channel

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# TO-220-1



DIM.	MILLIM	METERS	INCHE	HES
	MIN.	MAX.	MIN.	MAX.
Α	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
Е	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØΡ	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

# Note

DWG: 6031

•  $M^* = 0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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